#### Feature processing by photo-lithography: a top-dow approach

"**Photo-**lithography is a process used in microfabrication to pattern parts of a thin film. It uses light to transfer a geometric pattern from a photomask to a light-sensitive chemical "photoresist" (resist) on the substrate." *(Wikipedia)* 



Shorter wavelength: complexity of exposure optics, vaccum, cost issues... => SELF-ASSEMBLING ?

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features as small as 32 nm

## Oxide deposition (CVD) with DNA templates

When sample are exposed to a mixed vapor of Si(OEt)<sub>4</sub> (TEOS), H<sub>2</sub>O, and NH<sub>3</sub>, deposition of SiO<sub>2</sub> occurred selectively on the SiO<sub>2</sub> surface that was not covered by the DNA template, resulting in a negative-tone pattern of SiO<sub>2</sub>



To reverse the area selectivity of the CVD, propanol vapor was introduced and the relative humidity of the reaction chamber was increased. In this case, the CVD reaction selectively deposited  $SiO_2$  onto the DNA nanostructures to produce a positive-tone pattern

> J. Am. Chem. Soc., 2013, 135, 6778–6781 DOI: 10.1021/ja401785h

## Oxide deposition (CVD) with DNA templates

selective deposition of inorganic oxide onto a DNA nanostructure in the presence of a SiO2 substrate



#### +/- presence of water/n-propanol

Oxide deposition on different substrates with <20nm lateral resolution J. Am. Chem. Soc., 2013, 135, 6778–6781 DOI: 10.1021/ja401785h

#### HF « dry » etching of SiO<sub>2</sub> on DNA nanostructures

HF induced pattern transfer from DNA nanostructures



J. Am. Chem. Soc., 2011, 133 (31), pp 11868–11871

#### HF « dry » etching of $SiO_2$ on DNA nanostructures

HF induced pattern transfer from DNA nanostructures

$$SiO_2(s) + 4 HF(g) \rightarrow SiF_4(g) + 2 H_2O(g)$$

6 HF + 3 H<sub>2</sub>O  $\rightarrow$  3 HF<sub>2</sub><sup>-</sup> + 3 H<sub>3</sub>O<sup>+</sup> (deprotonation)

 $3 \text{ HF}_2^- + 3 \text{ H}_3\text{O}^+ + \text{SiO}_2 \rightarrow 2 \text{ HF} + \text{SiF}_4 + 5 \text{ H}_2\text{O}$  (etching)

- DNA may absorb water (up to +100% w/w!) (phosphate groups)
- but DNA may also serve as a diffusion barrier after deposition on SiO<sub>2</sub>...
- ... then H<sub>2</sub>O content in SiO<sub>2</sub> adsorbed DNA may favor or inhibit **HF dry etching**

J. Am. Chem. Soc., 2011, 133 (31), pp 11868–11871

#### HF induced pattern transfer from DNA nanostructures



Scale bars represent 100 nm.

J. Am. Chem. Soc., 2011, 133 (31), pp 11868–11871

## DNA Origami Mask for sub-10 nm lithography





Results from the A3DN project carried in Grenoble (R. Tiron & D. Gasparutto)

# DNA Origami Mask for sub-10 nm lithography



 Process based on the ionization of HF vapor by low pressurized alcohol vapor, which acts as a catalyst:

 $2HF(ads) + A(ads) \rightarrow HF_2^{-}(ads) + AH^{+}(ads)$ 

 $SiO_{2}(s) + 2HF_{2}^{-}(ads) + 2AH^{+}(ads)$  $\rightarrow SiF_{4}(ads) + 2H_{2}O(ads) + 2A(ads)$ 

• Low pressure in the chamber helps in desorbing the water released upon etching

Diagne C et al. ACS Nano. 2016 Jul 26;10(7):6458-63

## Sub 10 nm-large patterns transferred onto SiO<sub>2</sub>



- The longer HF exposition, the deeper etching...
- Nevertheless, some erosion is observed, and motif height is 7 times lower than expected
- Blocking of the etching reaction could be explained by the reaction of magnesium (initial DNA buffer) with the hot water vapors produced during the etching reaction to form magnesium hydroxide Mg(OH)<sub>2</sub>.

Diagne C et al. ACS Nano. 2016;10(7):6458-63

Sub 10 nm-resolution using HF vapor etching From 30 to 60 s at an etching rate of 0.2 nm/s SiO<sub>2</sub> etching limited to 20nm depth (MgF<sub>2</sub> adlayer?) Placement and orientation of individual DNA shapes on lithographically patterned surfaces

The problem of random DNA nanostructure deposition and lithographic scheme for addressing it:



Rothemund & al. *Nature Nanotechnology* 4, 557 - 561 (2009) doi:10.1038/nnano.2009.220